

1

**Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 19372
Application ID: 10065568
Title of Invention: SOLDER BUMP STRUCTURE AND
LASER REPAIR PROCESS FOR
MEMORY DEVICE
First Named Inventor: Kuo-Ming Chen
Domestic/Foreign Application: Domestic Application
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Deposit Account Name: WINSTON HSU



TRANSMITTAL FORM

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Submission Type: Utility
Patent Filing

Attorney Docket
Number:

NAUP0482USA

SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR MEMORY DEVICE

First Named Inventor: Kuo-Ming Chen

SUBMITTED BY

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I certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.

I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Attached Files:

declaration	NAUP0482DEC1.TIF
declaration	NAUP0482DEC2.TIF
specification	NAUP0482.xml
bibd-transmittal	NAUP0482apds.xml
patent-assignments	NAUP0482asgn.xml
fee-transmittal	NAUP0482fee.xml

Attached Image File(s):

NAUP0482DEC1.TIF
NAUP0482DEC2.TIF

Comments:

PATENT
Docket No. NA1P04821USA

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that

I believe I am the sole (if only one name appears below), or joint (if more than one name appears), original and first inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

"SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR
MEMORY DEVICE"

☒ The specification for the above entitled invention is filed herewith.

☐ The specification for the above entitled invention was filed previously
with application serial number, _____ Filing Date _____

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of the invention disclosed in this application in accordance with Title 37, Code of Federal Regulations, Section 1.56 (a). I further acknowledge the duty in any continuation-in-part application to disclose to the Patent and Trademark Office all information known to be material to the patentability of the invention disclosed in this application, as defined in 1.56, which became available to me between the filing date of the prior application and the filing date of this application.

PRIORITY CLAIM

☒ There is no claim of priority

☐ Claim of priority is based on the following:

POWER OF ATTORNEY

As a named inventor, I hereby appoint the following attorneys to prosecute this application and to transact all related business in the Patent and Trademark Office

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Combined Declaration and Power of Attorney, Page 1 of 1
DS:002CU0001101 FNPO-10001C-US

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued hereon

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FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

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TOTAL FEES AUTHORIZED: \$ 780

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Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

SUBMITTED BY

Authorized Name: WINSTON HSU
Electronic Signature Mark: VAEB-JMXX-8IIL
Date Signed: 20021031

BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	1001	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 10	1202	\$ 18	0	\$ 0
Independent Claims: 3	1201	\$ 84	0	\$ 0

